SERVICE-ORIENTED ORv3

LIQUID COOLING RACKS

Greater Compute Performance

Optimized Space

Better PUE

Lower OPEX

Quieter Operation

Ingrasys is committed to delivering cutting-edge, eco-friendly liquid cooling solutions that address the prevailing challenges in data center cooling while lowering the environmental impacts to a minimal level. As a one-stop solution provider, Ingrasys offers comprehensive solutions covering the entire spectrum of cooling solutions, from component level to rack level. These solutions feature flexible and modular design, allowing for rapid assembly and configuration based on specific requirements.

FEATURES

- Modular Design
- Integrate into Different Data Center Infrastructure
- Hot-swappable Redundant Units
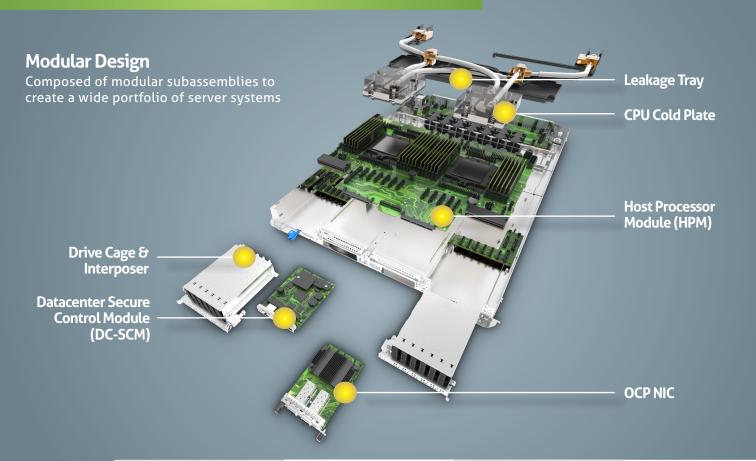- Direct to Chip Liquid Cooling
- Front Access IT Equipment

ingrasys®

Ingrasy Advanced Cooling Solution

LIQUID-TO-AIR SOLUTION

9+1 Redundant Fans

Rear Door Heat Exchanger

Blind-mate Manifold

Reservoir Pumping Unit (RPU)

LA0452

LA0763

		LA0452 All Heat to Air, No Facility Liquid	LA0763 All Heat to Air (Side Car), No Facility Liquid
FACILITY	COLD/ HOT-AISLE	Y	Y
	FACILITY LIQUID	N	N
SERVER	TYPE	Compliant with ORv3 IT Gear Spec	
RPU/CDU	TYPE	Reservoir Pumping Unit (RPU)	
	SIZE	4RU, 19" and 21" Compatible	
	POWER	Support 48VDC or 220VAC	
	HOT-SWAP	Pump/PSU/Control Board	
	REDUNDANCY (N+1)	Pump/PSU	
MANIFOLD	CONNECTION	Blind-mate Quick Disconnection	
COOLING	COOLING CAPACITY	45kw	76kw
	FAN (N+1)	9+1	17+1

LIQUID-TO-LIQUID SOLUTION

Rear Door Heat Exchanger

Blind-mate Manifold

Coolant Distribution Unit (CDU)

LL1000

LL1001

LL1000
All Heat to Facility Liquid & Air

LL1001
All Heat to Facility Liquid

LL1000	LL1001		
Y	N	COLD/ HOT-AISLE	FACILITY
Y	Y	FACILITY LIQUID	
Compliant with ORv3 IT Gear Spec		TYPE	SERVER
Coolant Distribution Unit (CDU)		TYPE	RPU/CDU
4RU, 19" and 21" Compatible		SIZE	
Support 48VDC or 220VAC		POWER	
Pump/PSU/Control Board		HOT-SWAP	
Pump/PSU		REDUNDANCY (N+1)	
Blind-mate Quick Disconnection		CONNECTION	MANIFOLD
100kw	100kw	COOLING CAPACITY	COOLING
N/A	N/A	FAN (N+1)	

LIQUID COOLING SERVER

Modular Design

Composed of modular subassemblies to create a wide portfolio of server systems

- Leakage Tray
- CPU Cold Plate
- Host Processor Module (HPM)
- Drive Cage & Interposer
- Datacenter Secure Control Module (DC-SCM)
- OCP NIC

	SV1121A	SV1121I	SV2121A	SV2121I
Form Factor	1 OU		2 OU	
Processor	2 x 4th Gen AMD EPYC™ Processors	2 x 4th Gen Intel® Xeon® Scalable Processors	2 x 4th Gen AMD EPYC™ Processors	2 x 4th Gen Intel® Xeon® Scalable Processors
Memory	24 x DDR5 RDIMMs 2 x E3.S CXL Memory Modules (SKU 3)	32 x DDR5 RDIMMs 2 x E3.S CXL Memory Modules (SKU 3)	24 x DDR5 RDIMMs	32 x DDR5 RDIMMs
Storage	SKU 1: 12 x E1.S SSDs SKU 2: 6 x E1.S SSDs SKU 3: 6 x E1.S SSDs 2 x 22110 M.2 Boot Drives		2 x 22110 M.2 Boot Drives	
Expansion Slot	SKU 1 & 3: 2 x PCIe 5.0 x16 FHHL Slots 1 x PCIe 5.0 x16 OCP NIC 3.0 SKU 2: 2 x PCIe 5.0 x16 FHHL Slots 2 x PCIe 5.0 x16 LP/HHHL with Riser Card Slots 1 x PCIe 5.0 x16 OCP NIC 3.0		2 x PCIe 5.0 x16 FHHL Slots 8 x PCIe 5.0 x16 LP/HHHL With Riser Card Slots	
I/O Ports	1 x 1GbE/RJ45 Management Port 1 x USB 2.0 1 x Mini Display Port 1 x Reset Button 1 x Power Button with LED 1 x UID Button with LED		1 x 1GbE/RJ45 Management Port 1 x USB 2.0 1 x Mini Display Port 1 x Reset Button 1 x Power Button with LED 1 x UID Button with LED	
Power Supply	Centralized 48V Bus Bar with PDB		Centralized 48V Bus Bar with PDB	
Dimensions (H x W x D)	1.75" x 21.14" x 31.76" / 44.7mm x 537.0mm x 806.7mm		3.68" x 21.14" x 31.76" / 93.5mm x 537.0mm x 806.7mm	